NUP4301MR6, SZNUP4301MR6

Low Capacitance Diode Array for ESD Protection in Four Data Lines

SZ/NUP4301MR6T1G is a micro–integrated device designed to provide protection for sensitive components from possible harmful electrical transients; for example, ESD (electrostatic discharge).

Features

- Low Capacitance (1.5 pf Maximum Between I/O Lines)
- Single Package Integration Design
- Provides ESD Protection for JEDEC Standards JESD22 Machine Model = Class C Human Body Model = Class 3B
- Protection for IEC61000-4-2 (Level 4) 8.0 kV (Contact) 15 kV (Air)
- Ensures Data Line Speed and Integrity
- Fewer Components and Less Board Space
- Direct the Transient to Either Positive Side or to the Ground
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- This is a Pb–Free Device*

Applications

- USB 1.1 and 2.0 Data Line Protection
- T1/E1 Secondary IC Protection
- T3/E3 Secondary IC Protection
- HDSL, IDSL Secondary IC Protection
- Video Line Protection
- Microcontroller Input Protection
- Base Stations
- I²C Bus Protection

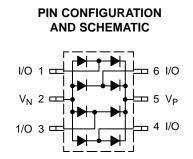


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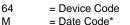


SC-74 CASE 318F



MARKING DIAGRAM





= Pb-Free Package

(Note: Microdot may be in either location.

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NUP4301MR6T1G	SC-74 (Pb-Free)	3,000 / Tape & Reel
SZNUP4301MR6T1G	SC-74 (Pb-Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MAXIMUM RATINGS (Each Diode) ($T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit	
Reverse Voltage	V _R	70	Vdc	
Forward Current	١ _F	200	mAdc	
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc	
Repetitive Peak Reverse Voltage	V _{RRM}	70	V	
Average Rectified Forward Current (Note 1) (averaged over any 20 ms period)	I _{F(AV)}	715	mA	
Repetitive Peak Forward Current	I _{FRM}	450	mA	
Non-Repetitive Peak Forward Current $t = 1.0 \ \mu s$ $t = 1.0 \ ms$ $t = 1.0 \ S$	I _{FSM}	2.0 1.0 0.5	A	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{ ext{ heta}JA}$	556	°C/W
Lead Solder Temperature, Maximum 10 Seconds Duration	TL	260	°C
Junction Temperature	TJ	-40 to +150	°C
Storage Temperature	T _{stg}	–55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise noted) (Each Diode)

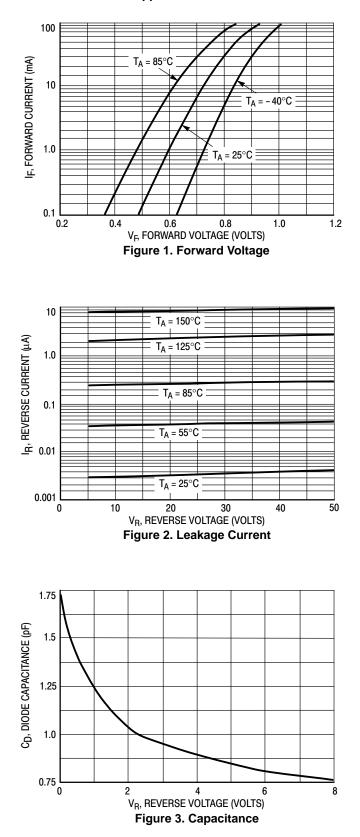
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Reverse Breakdown Voltage (I _(BR) = 100 μA)	V _(BR)	70	-	-	Vdc
Reverse Voltage Leakage Current ($V_R = 70 \text{ Vdc}$) ($V_R = 25 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$) ($V_R = 70 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$)	I _R	- - -	- - -	2.5 30 50	μAdc
Capacitance (between I/O pins) (V _R = 0 V, f = 1.0 MHz)	CD	-	0.8	1.5	pF
Capacitance (between I/O pin and ground) $(V_R = 0 V, f = 1.0 MHz)$	CD	-	1.6	3	pF
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 50 \text{ mAdc})$ $(I_F = 150 \text{ mAdc})$	V _F	- - - -	- - - -	715 855 1000 1250	mV _{dc}

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

3. Include SZ-prefix devices where applicable.

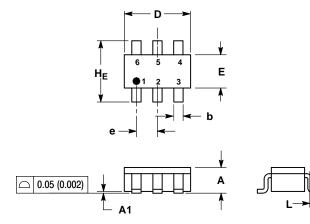
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Curves Applicable to Each Cathode



PACKAGE DIMENSIONS

SC-74 CASE 318F-05 ISSUE N

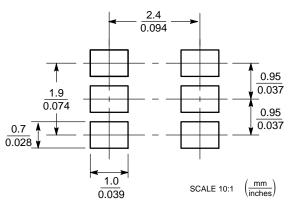


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
- THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.37	0.50	0.010	0.015	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
Е	1.30	1.50	1.70	0.051	0.059	0.067	
e	0.85	0.95	1.05	0.034	0.037	0.041	
Г	0.20	0.40	0.60	0.008	0.016	0.024	
ΗE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	-	10°	0°	-	10°	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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